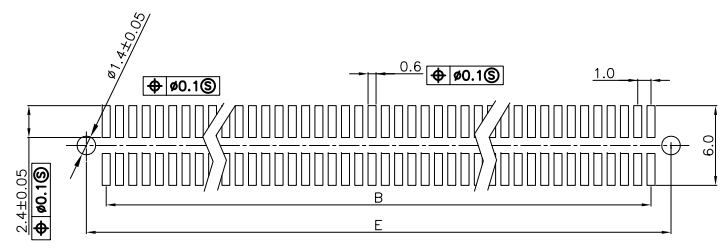
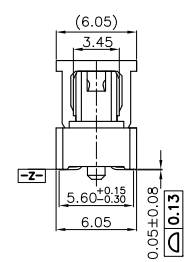
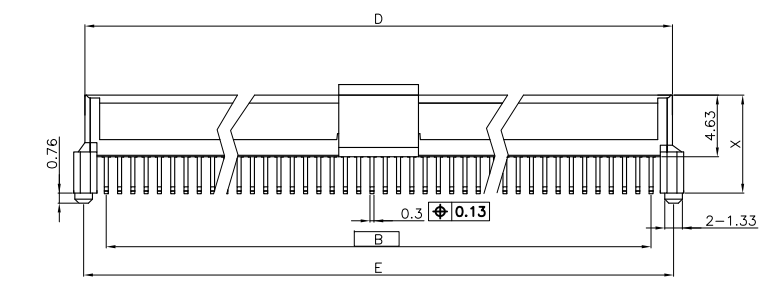
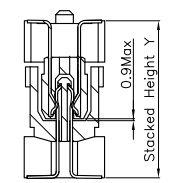
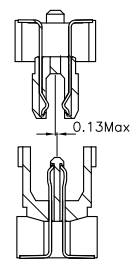
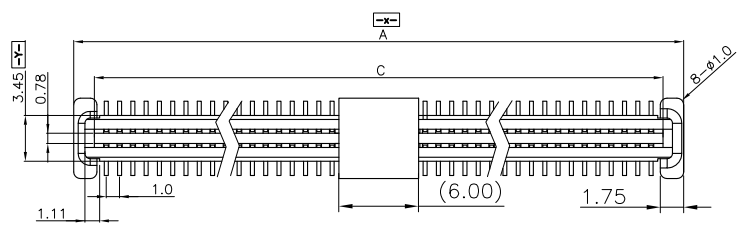


REV.	SPECIFICATION	ECN NO.	APPD.
R3		ECN190121	



P.C.Board Layout

2348- **xx** **G** **xx** **D** **x** **N** **x** **T** - **x**
 Series Position G: Gold Plated C: Selective Gold Plated
 00: G/F
 10: 10μ
 15: 15μ
 30: 30μ
 D: SMD Type
 P: With Post N: Without Post
 T: Tape & Reel Package
 P: Plastic Pad(Black)
 S: Mylar
 Code 1
 Code 2
 Code 3
 Code 4
 Blank: Black
 N: Beige

Material and Plating:
 Housing: LCP, UL94V-0, BLACK
 Contact: Phosphor copper
 Gold Plated on Contact Area and 80u" Min. Tin or Gold
 Flash Plated on solder tail over Nickel 50u" Min.
Electrical Characteristics:
 Current Rating: 0.5 AMP.
 Dielectric Withstanding Voltage: AC 500V For 1 minute.
 Insulator Resistance: 100MΩ min. at DC 100V.
 Contact Resistance: 40mΩ max. at DC 1mA.
 Operating Temperature: -40°C~+85°C .
***RoHS Compliant**

"x" Available Position									
Code				Pos.	Dimension				
H1	H2	H3	H4		A	B	C	D	E
				14	10.90	6.00	7.80	9.22	9.40
				18	12.90	8.00	9.80	11.22	11.40
*	*	*	*	20	13.90	9.00	10.80	12.22	12.40
*	*	*	*	30	18.90	14.00	15.80	17.22	17.40
*	*	*	*	34	20.90	16.00	17.80	19.22	19.40
				36	21.90	17.00	18.80	20.22	20.40
*	*	*	*	40	23.90	19.00	20.80	22.22	22.40
				50	28.90	24.00	25.80	27.22	27.40
*	*	*	*	64	35.90	31.00	32.80	34.22	34.40
*	*	*	*	80	43.90	39.00	40.80	42.22	42.40
				84	45.90	41.00	42.80	44.22	44.40
				100	53.90	49.00	50.80	52.22	52.40

code:1~4 X	1	1	1	2	2	2	3	3	3	4	4	4
2348	5.37	5.37	5.37	7.37	7.37	7.37	8.37	8.37	8.37	10.37	10.37	10.37
code:1~3 X	1	2	3	1	2	3	1	2	3	1	2	3
2349	6.35	7.35	8.35	6.35	7.35	8.35	6.35	7.35	8.35	6.35	7.35	8.35
stacked height Y	8.0	9.0	10.0	10.0	11.0	12.0	11.0	12.0	13.0	13.0	14.0	15.0

Tolerances	Dwg No.	2348-D0000-002	Title:			
x = ±0.5	Projection		2348 Series			
.x = ±0.25	Unit	mm	Board to Board 1.0mm			
.xx = ±0.15	Scale	1:1	Female Type			
	Drawn By	QHX 01/21'19	 OUPIN ELECTRONIC(KUNSHAN) CO., LTD. P/N: 2348-xxG(C)xxDxNxT-x			